

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	58	((("711"/\$.ccls. and module) and row) and ((ic chip) near3 arrang\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:29
L2	158	(711/5.ccls. and module) and (arrang\$4 layout)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:29
L3	378	711/5.ccls. and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:29
L4	3	(memory and module and ((IC chip) with arrang\$5)) and (bilateral near2 symmetr\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:29
L5	0	((memory and module and ((IC chip) with arrang\$5)) and ((IC chip) with row)) and (bilateral near2 symmetr\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:29
L6	100	((memory and module and packag\$3) and (first adj row) and (second adj row)) and lateral\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:29
L7	17	(memory and module and packag\$3) and (lateral\$2 near2 hal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:30
L8	97	((memory and module and packag\$3) and TSOP) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:30
L9	12	((memory and module and packag\$3) and TSOP) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2)) and (((memory and module and packag\$3) and gigabyte) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:30

S1	3324	memory and packag\$3 and board and (register with address\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/18 22:05
S2	1825	memory and packag\$3 and (circuit near3 board) and (register with address\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/05 15:35
S3	24	(memory and packag\$3 and (circuit near3 board) and ((register with address\$3) same (control\$4 near3 bus))) and (first near3 half) and (second near3 half)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/05 15:37
S4	2019	(memory near2 module) and pack\$4 and (pcb (printed near3 circuit near3 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/18 22:07
S5	155	((memory near2 module) and pack\$4 and (pcb (printed near3 circuit near3 board))) and ((control\$4 near3 bus) with register)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:03
S6	458	(memory and module and packag\$3) and TSOP	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:06
S7	3	((memory and module and packag\$3) and TSOP) and gigabyte	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:09
S8	626	(memory and module and packag\$3) and gigabyte	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:10
S9	3683	(memory and module and packag\$3) and (wide width) and (height high) and inch\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:11

S10	1	((memory and module and packag\$3) and TSOP) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2)) and (((memory and module and packag\$3) and gigabyte) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:12
S11	51	(memory and module and packag\$3) and (bilateral\$2 with symmetr\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:13
S12	27	(memory and module and packag\$3) and (bilateral with symmetr\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:20
S13	1	((memory and module and packag\$3) and gigabyte) and (((memory and module and packag\$3) and TSOP) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 13:21
S14	76	((memory and module and packag\$3) and TSOP) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 16:41
S15	145	((memory and module and packag\$3) and gigabyte) and ((memory and module and packag\$3) and (wide width) and (height high) and inch\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 16:55
S16	422	memory and packag\$3 and (circuit near3 board) and ((register with address\$3) same (control\$4 near3 bus))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 17:25
S17	312	(memory and packag\$3 and (circuit near3 board) and ((register with address\$3) same (control\$4 near3 bus))) and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 17:25
S18	25562	memory and module and packag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 20:03

S19	357	(memory and module and packag\$3) and (first adj row) and (second adj row)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 20:04
S20	2	(memory and module and packag\$3) and (lateral\$2 near2 half)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 20:05
S21	2	(memory and module and packag\$3) and (lateral\$2 near2 hal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 20:05
S22	65	((memory and module and packag\$3) and (first adj row) and (second adj row)) and lateral\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/01 20:05
S23	4101	memory and module and ((IC chip) with arrang\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/18 20:00
S24	894	(memory and module and ((IC chip) with arrang\$5)) and ((IC chip) with row)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/18 20:00
S25	0	((memory and module and ((IC chip) with arrang\$5)) and ((IC chip) with row)) and (bilateral near2 symmetr\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/18 20:01
S26	3	(memory and module and ((IC chip) with arrang\$5)) and (bilateral near2 symmetr\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/18 20:01
S27	17922	"711"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/21 11:49
S28	4521	"711"/\$.ccls. and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/21 11:50

S29	1369	("711"/\$.ccls. and module) and row	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/21 11:51
S30	46	((("711"/\$.ccls. and module) and row) and ((ic chip) near3 arrang\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/21 12:05
S31	775	711/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/21 12:08
S32	293	711/5.ccls. and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/21 12:08
S33	136	(711/5.ccls. and module) and (arrang\$4 layout)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/16 18:15
S34	2	"6751113".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 12:25